

Hysol® Chip-On-Board Glob Tops

Product	Description/Application	Pot Life @ 25°C	Recommended Cure	Tg (°C)	CTE (1) (PPM/°C)	Filler Type	Storage Temp (°C)
E01016™	UL94-V0 encapsulant for smart cards and watch ICs. Non-abrasive filler allows for grinding if necessary.	3 months	20 min @ 150°C	115	46	Calcium Carbonate	4
E01060™	Low glob formulation for lower CTE and lower ionic than E01016 content for more demanding applications.	25 days	4-6 hrs @ 125°C	125	40	Calcium Carbonate	4
E01061™	Medium glob version of E01060.	25 days	4-6 hrs @ 125°C	125	40	Calcium Carbonate	4
E01062™	High glob version of E01060.	25 days	4-6 hrs @ 125°C	125	40	Calcium Carbonate	4
E01072™	One component, high performance encapsulant with high Tg and low extractable ionics.	1 month	5 min @ 140/150°C	135	43	Silica	4
E01080™	Low CTE version of E01016.	3 months	20 min @ 150°C	121	35	Silica	4